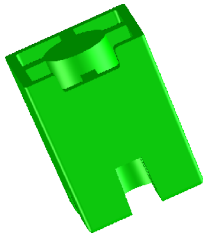
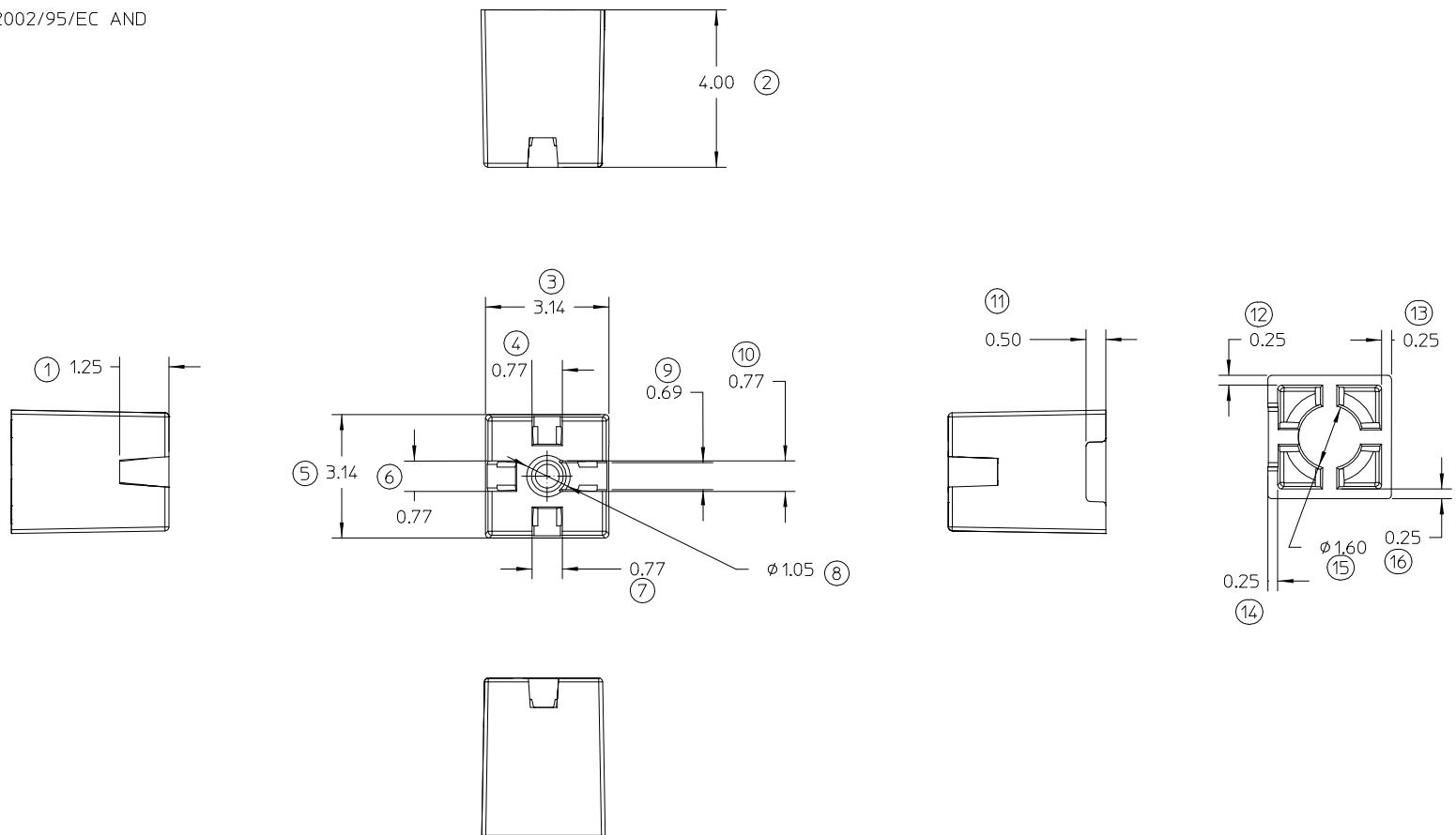


NOTE:
1. MATERIAL :LCP-LDS, VECTRA E840ILDS, 40% MINERAL
FILLED LASER DIRECT STRUCTURING GRADE,UL94V-0;
2.GENERAL TOLERANCE :+/-0.05MM
3.PRODUCT COMPLANT TO ROHS DIERTIVE 2002/95/EC AND
ELV DIRECTIVE2000/53/EC

REV	ZONE	EC NO.	DISCRIPTION	DATE
A	ALL	ABU2011-0087	FIRST RELEASE	20110407
B	ALL	ABU2011-0104	DRAWING UPDATE	20110516

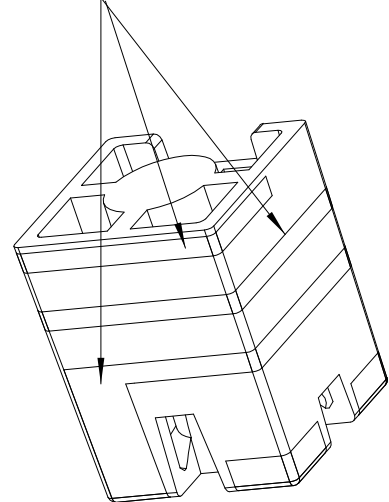


gen1

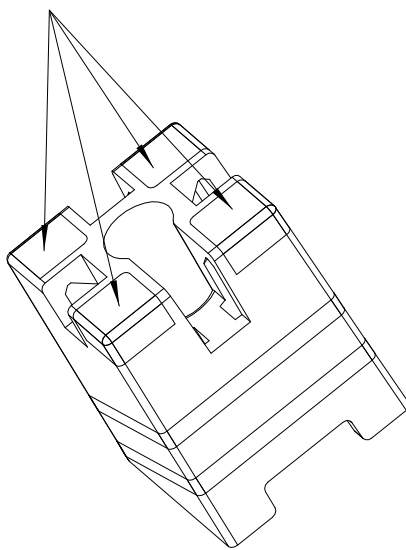


ENTER DESCRIPTION EC NO: DRWN: CHKD: APPR:		DESCRIPTION	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE 8:1	DESIGN UNITS	THIRD ANGLE PROJECTION	
			F_A=0 F_B=0 F_C=0 F_P=0	mm	INCH	DRAWN BY DATE		TITLE			
				4 PLACES ±	±	COOPRZHOU 20110516					
				3 PLACES ±	±	CHECKED BY DATE		2.4GHZ SMD ON GROND ANTENNA CARRIER			
				2 PLACES ±	±	ERIC SHI 20110516					
				1 PLACE ±	±	APPROVED BY DATE		molex MOLEX INCORPORATED			
ANGULAR ± °		WELSON TAN 20110516									
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
				SEE SHIFT2		SD-47948-001		1 OF 3			
B		REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

LDS PATTERN



PATTERN FOR SOLDERING



Notes:

1. PLATING SPEC:

Cu: 12 μ m MINIMUM;

MID P Ni: 2 μ m MINIMUM;

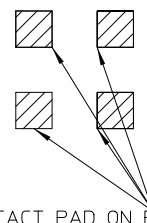
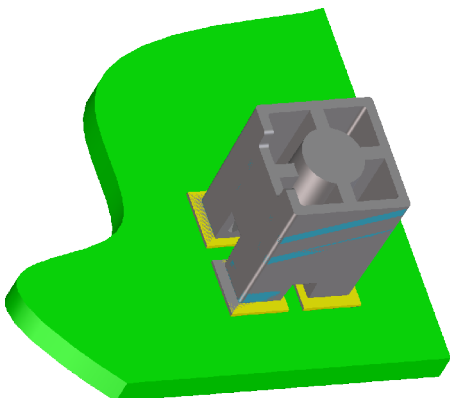
Au : 0.1 μ m MINIMUM

2. OVER FLOWING OF PATTERN PROFILE AFTER PLATING:0.03 μ m MAXIMUM.

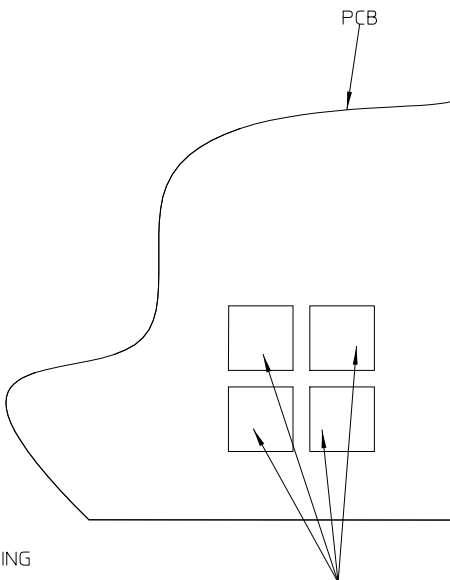
Table-1

4	479480004	2.4 GHZ SMG ON GROUD (AFTER MOLDING)	1
3	479480003	2.4 GHZ SMG ON GROUD (AFTER LDS)	1
2	479480002	2.4 GHZ SMG ON GROUD (AFTER PLATING)	1
1	479480001	2.4 GHZ SMG ON GROUD (After RF test)	1
Pos	Material Number	Description	Qty

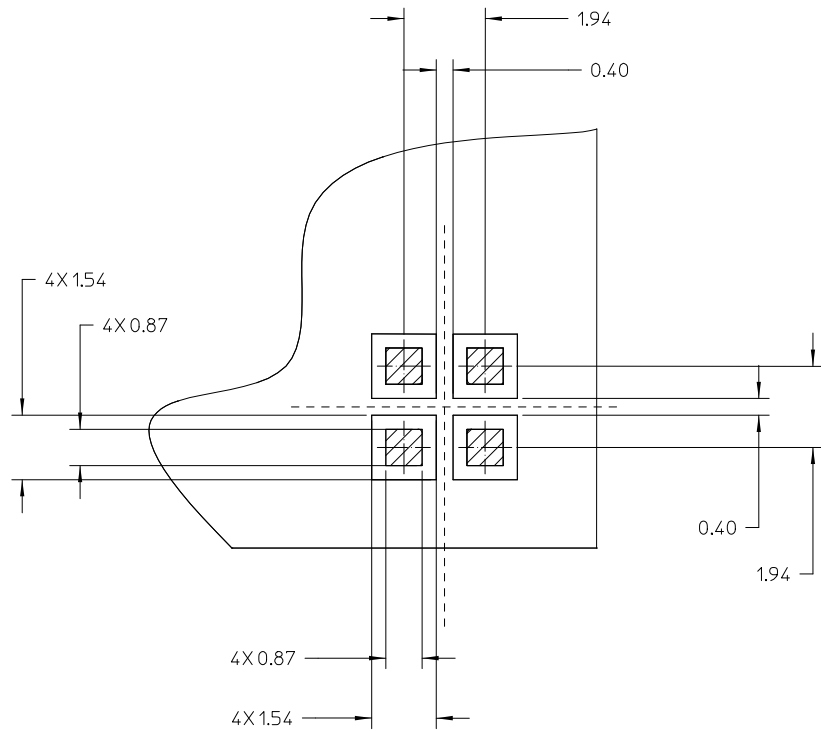
ENTER DESCRIPTION			DESCRIPTION	QUALITY SYMBOLS		GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
EC NO:				 =0		mm	INCH	DRAWN BY COOPERZHOU		DATE 20110516		TITLE 2.4 GHZ SMG ON GROUD ANTENNA PATTERN			
DRWN:								CHECKED BY ERIC SHI		DATE 20110516					
CHKD:					 =0				APPROVED BY		DATE		molex MOLEX INCORPORATED		
APPR:									WESTON TAN		20110516				
REV				 =1	ANGULAR ± °			MATERIAL NO.		DOCUMENT NO.		SHEET NO.			
					DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			See Table-1		SD-47948-001		2 OF 3			
								SIZE A 4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					



THE CONTACT PAD ON PRODUCT FOR SOLDERING



THE FOOTPRINT ON PWB FOR SOLDERING



RECOMENED PWB PATTERN LAYOUT

ENTER DESCRIPTION EC NO: DRWN: CHKD: APPR: B	DESCRIPTION REV	QUALITY SYMBOLS F _A =0 F _C =0 F _P =0	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE		SCALE 8:1	DESIGN UNITS	THIRD ANGLE PROJECTION		
				mm	INCH	DRAWN BY	DATE	TITLE FOOTPRINT FOR 2.4 SMD ON GROND ANTENNA				
			4 PLACES	±	±	COOPRZHOU	20110516					
			3 PLACES	±	±	CHECKED BY	DATE	MOLEX INCORPORATED				
			2 PLACES	±	±	ERIC SHI	20110516					
			1 PLACE	±	±	APPROVED BY	DATE	DOCUMENT NO. SD-47948-001				
			ANGULAR ± °			WELSON TAN	20110516					
			DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			MATERIAL NO.		SHEET NO. 3 OF 3				
						SEE SHIFT 2						
						SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					